

Serial No. - 09/651,498  
Art Unit - 1763

### Amendments to the Specification

Please delete the two paragraphs added to the specification (page 10, line 26) in the amendment of April 2, 2003.

-- As is clearly illustrated in Figs. 2 and 4, the rotary spindle 24 defines a lower heat regulation zone 24A and an upper heat regulation zone 24B. The rotary spindle 24 is mechanically coupled to the rotary drive motor 22 in the lower heat regulation zone 24A. The heat regulating flange 30 is positioned in the lower heat regulation zone 24A while the heat regulating element 50 is positioned in the upper heat regulation zone 24B. The substantially cylindrical heat regulation void 55 is defined about a portion of the rotary spindle 24 in the upper heat regulation zone 24B.

The heat regulating element 50 defines an open framework (illustrated with most clarity in Fig. 4) arranged about the rotary spindle 24 such that lower and upper bounds 50A, 50B of the heat regulating element 50 are open to the substantially cylindrical heat regulation void 55 along a cylindrical projection 62 extending from the lower heat regulation zone 24A to the upper heat regulation zone 24B. As is noted above and as is clearly illustrated by Figs. 2 and 4, the dimensions of the cylindrical heat regulation void 55 defined by the heat regulating element 50 are established so as to avoid substantial degradation of the exhaust gas flow profile defined by the wafer processing bowl. Flow of exhaust gases are permitted along the exhaust gas flow profile defined by the wafer processing bowl from the lower heat regulation zone 24A, beyond the lower bound 50A of the heat regulating element 50 through the upper heat regulation zone 24B beyond the upper bound 50B of the heat regulating element 50.

Finally, as is clearly illustrated in Fig. 2, the substantially cylindrical heat regulation void 55 is defined along a limited extent of the rotary spindle 24, displaced a substantial distance from the heat regulating flange 30. The distance by which the substantially cylindrical heat regulation void 55 is displaced from the heat regulating flange 30 comprises a major portion of a length of the rotary spindle 24 defined between the wafer support 70 and the heat regulating flange 30. --